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## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



## OptiMOS<sup>®</sup>-P Small-Signal-Transistor Feature

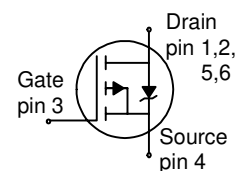
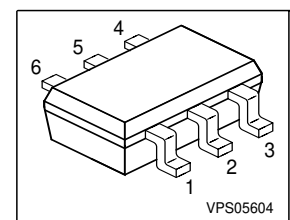
- P-Channel
- Enhancement mode
- Super Logic Level (2.5 V rated)
- 150°C operating temperature
- Avalanche rated
- dv/dt rated
- Pb-free lead plating; RoHS compliant
- Qualified according to AEC Q101
- Halogen-free according to IEC61249-2-21



### Product Summary

$V_{DS}$	-20	V
$R_{DS(on)}$	175	m $\Omega$
$I_D$	-1.5	A

PG-SOT-363



Type	Package	Tape and Reel inf	Marking
BSV 236SP	PG-SOT-363	H6327:3000pcs/r.	X2s

### Maximum Ratings, at $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current	$I_D$		A
$T_A=25\text{ }^\circ\text{C}$		-1.5	
$T_A=70\text{ }^\circ\text{C}$		-1.2	
Pulsed drain current	$I_D \text{ puls}$	-6	
$T_A=25\text{ }^\circ\text{C}$			
Avalanche energy, single pulse	$E_{AS}$	9.5	mJ
$I_D=-1.5\text{ A}$ , $V_{DD}=-10\text{ V}$ , $R_{GS}=25\text{ }\Omega$			
Reverse diode dv/dt	dv/dt	-6	kV/ $\mu\text{s}$
$I_S=-1.5\text{ A}$ , $V_{DS}=-16\text{ V}$ , $di/dt=200\text{ A}/\mu\text{s}$ , $T_{jmax}=150\text{ }^\circ\text{C}$			
Gate source voltage	$V_{GS}$	$\pm 12$	V
Power dissipation	$P_{tot}$	0.56	W
$T_A=25\text{ }^\circ\text{C}$			
Operating and storage temperature	$T_j, T_{stg}$	-55... +150	$^\circ\text{C}$
IEC climatic category; DIN IEC 68-1		55/150/56	
ESD Class JESD22-A114-HBM		Class 0	

**Thermal Characteristics**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Characteristics</b>					
Thermal resistance, junction - soldering point	$R_{thJS}$	-	-	90	K/W
SMD version, device on PCB:	$R_{thJA}$				
@ min. footprint		-	-	220	
@ 6 cm <sup>2</sup> cooling area <sup>1)</sup>		-	-	110	

**Electrical Characteristics, at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Static Characteristics</b>					
Drain-source breakdown voltage $V_{GS}=0, I_D=-250\mu\text{A}$	$V_{(BR)DSS}$	-20	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D=-8\mu\text{A}$	$V_{GS(th)}$	-0.6	-0.9	-1.2	
Zero gate voltage drain current $V_{DS}=-20\text{V}, V_{GS}=0, T_j=25^\circ\text{C}$ $V_{DS}=-20\text{V}, V_{GS}=0, T_j=150^\circ\text{C}$	$I_{DSS}$	-	-0.1 -10	-1 -100	$\mu\text{A}$
Gate-source leakage current $V_{GS}=-12\text{V}, V_{DS}=0$	$I_{GSS}$	-	-10	-100	
Drain-source on-state resistance $V_{GS}=-2.5\text{V}, I_D=-0.8\text{A}$	$R_{DS(on)}$	-	193	285	$\text{m}\Omega$
Drain-source on-state resistance $V_{GS}=-4.5, I_D=-1.5\text{A}$	$R_{DS(on)}$	-	131	175	

<sup>1)</sup> Device on 40mm\*40mm\*1.5mm epoxy PCB FR4 with 6cm<sup>2</sup> (one layer, 70  $\mu\text{m}$  thick) copper area for drain connection. PCB is vertical without blown air;  $t \leq 10$  sec.

**Electrical Characteristics**, at  $T_j = 25\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Dynamic Characteristics**

Transconductance	$g_{fs}$	$ V_{DS}  \geq 2 *  I_D  * R_{DS(on)max}$ $I_D = -1.2A$	2.2	4.4	-	S
Input capacitance	$C_{iss}$	$V_{GS} = 0, V_{DS} = -15V,$ $f = 1MHz$	-	228	-	pF
Output capacitance	$C_{oss}$		-	92	-	
Reverse transfer capacitance	$C_{rss}$		-	75	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -10V, V_{GS} = -4.5V,$ $I_D = -1A, R_G = 6\Omega$	-	5.7	8.5	ns
Rise time	$t_r$		-	8.5	12.7	
Turn-off delay time	$t_{d(off)}$		-	14.1	21.1	
Fall time	$t_f$		-	12.2	18.3	

**Gate Charge Characteristics**

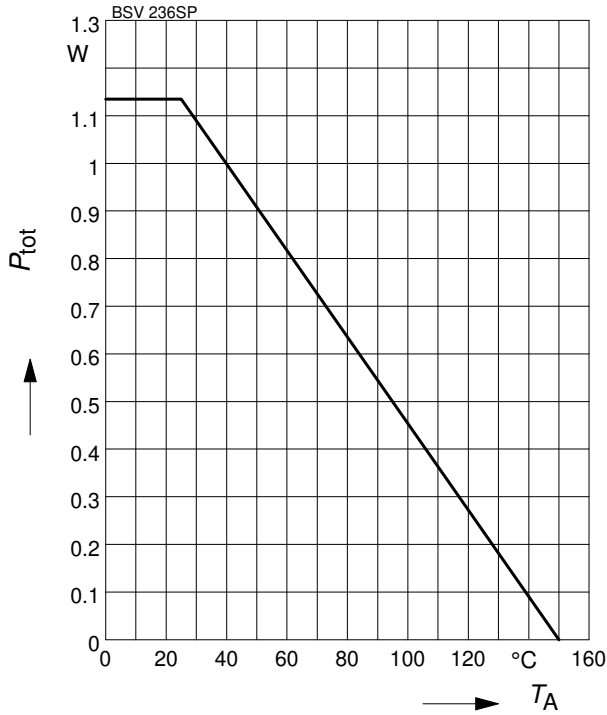
Gate to source charge	$Q_{gs}$	$V_{DD} = -10V, I_D = -1.5A$	-	-0.4	-0.6	nC
Gate to drain charge	$Q_{gd}$		-	-1.8	-2.7	
Gate charge total	$Q_g$	$V_{DD} = -10V, I_D = -1.5A,$ $V_{GS} = 0 \text{ to } -4.5V$	-	-3.8	-5.7	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = -10V, I_D = -1.5A$	-	-1.6	-	V

**Reverse Diode**

Inverse diode continuous forward current	$I_S$	$T_A = 25\text{ °C}$	-	-	-0.11	A
Inverse diode direct current, pulsed	$I_{SM}$		-	-	-6	
Inverse diode forward voltage	$V_{SD}$	$V_{GS} = 0,  I_F  =  I_D $	-	0.88	1.3	V
Reverse recovery time	$t_{rr}$	$V_R = -10V,  I_F  =  I_D ,$ $di_F/dt = 100A/\mu s$	-	16.4	20.5	ns
Reverse recovery charge	$Q_{rr}$		-	3.4	4.3	nC

### 1 Power dissipation

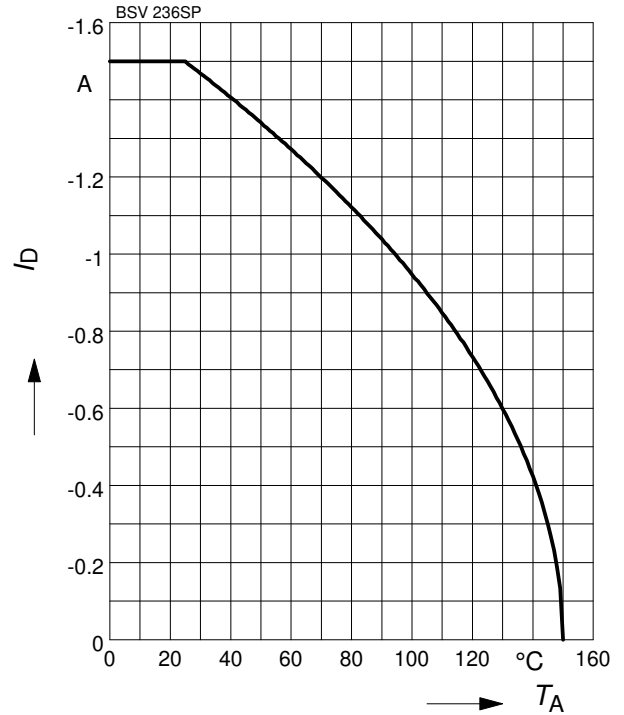
$$P_{tot} = f(T_A)$$



### 2 Drain current

$$I_D = f(T_A)$$

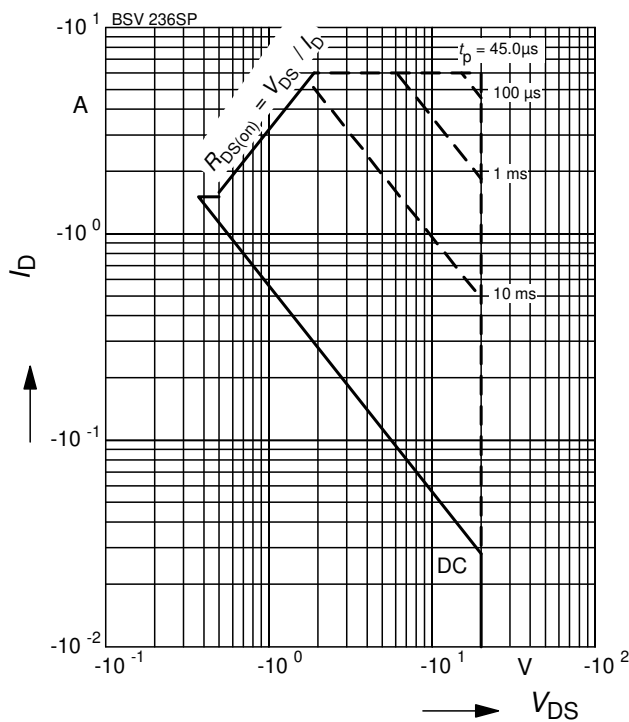
parameter:  $|V_{GS}| \geq 4.5 \text{ V}$



### 3 Safe operating area

$$I_D = f(V_{DS})$$

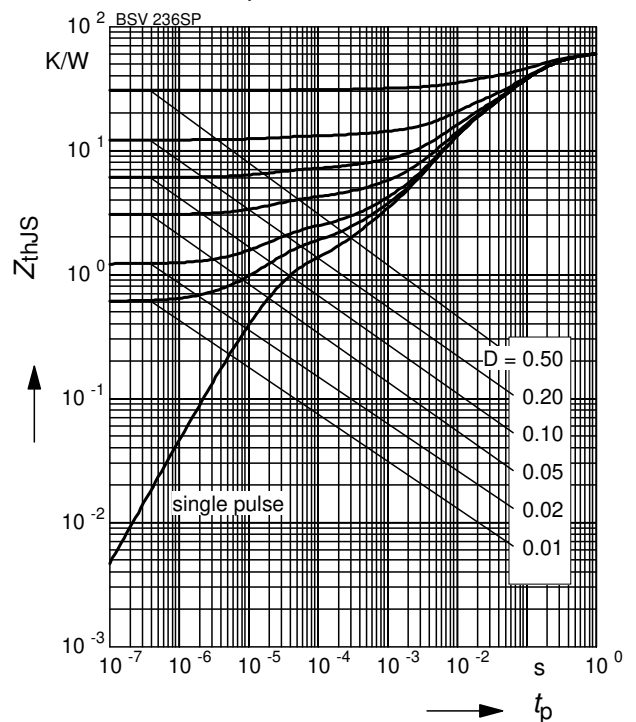
parameter:  $D = 0, T_A = 25 \text{ °C}$



### 4 Transient thermal impedance

$$Z_{thJS} = f(t_p)$$

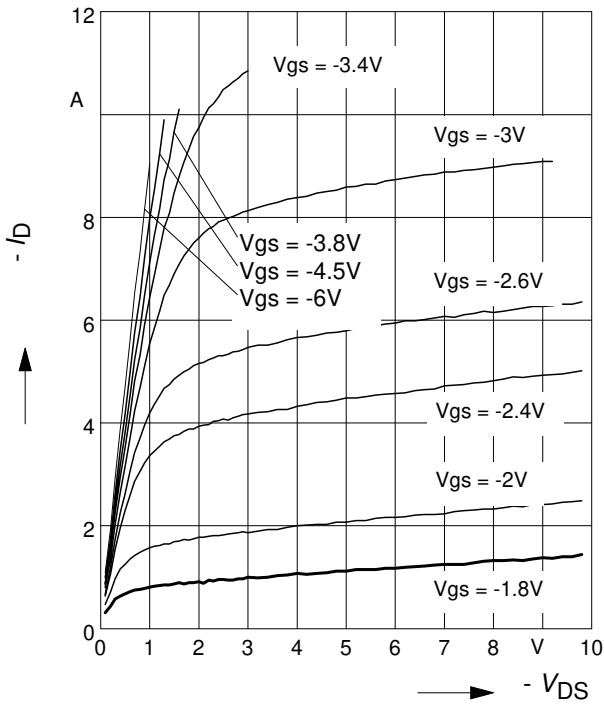
parameter:  $D = t_p/T$



**5 Typ. output characteristic**

$I_D = f(V_{DS}); T_j=25^\circ\text{C}$

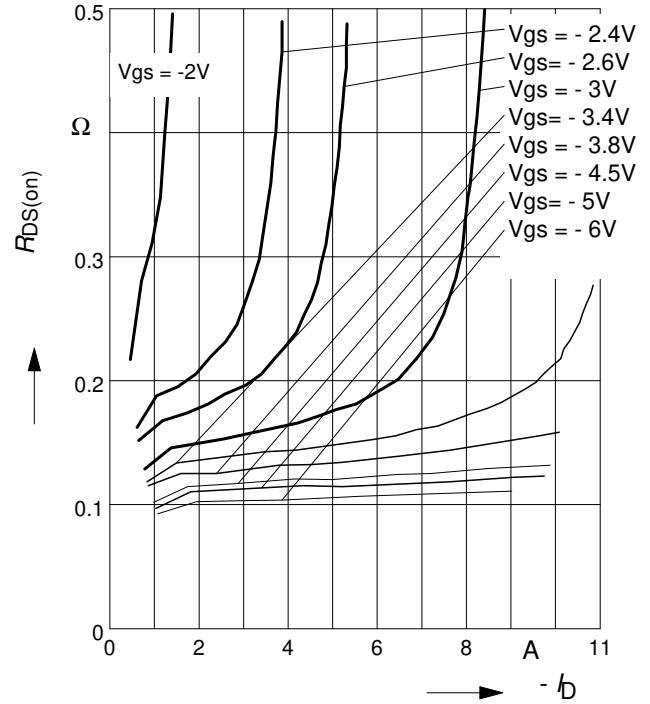
parameter:  $t_p = 80 \mu\text{s}$



**6 Typ. drain-source on resistance**

$R_{DS(on)} = f(I_D)$

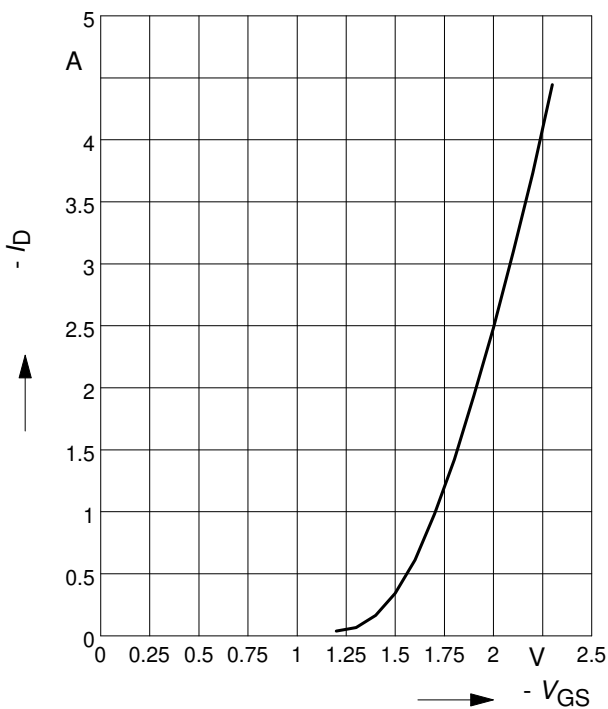
parameter:  $V_{GS}$



**7 Typ. transfer characteristics**

$I_D = f(V_{GS}); |V_{DS}| \geq 2 \times |I_D| \times R_{DS(on)max}$

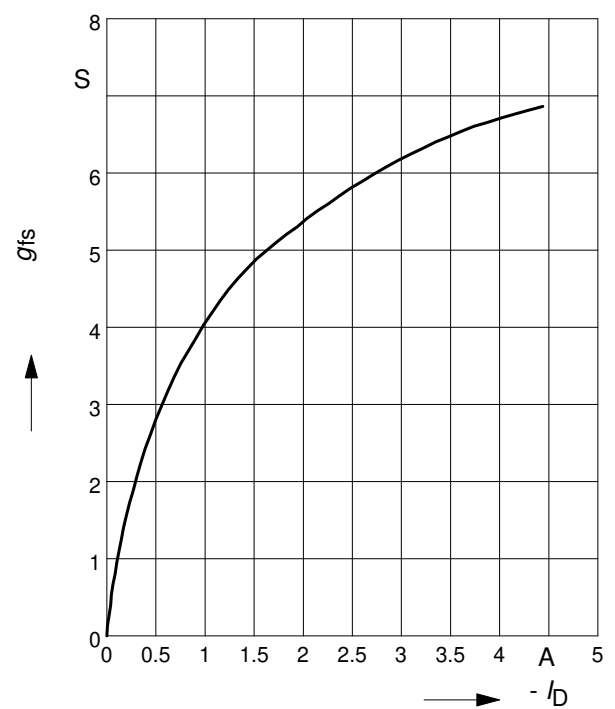
parameter:  $t_p = 80 \mu\text{s}$



**8 Typ. forward transconductance**

$g_{fs} = f(I_D); T_j=25^\circ\text{C}$

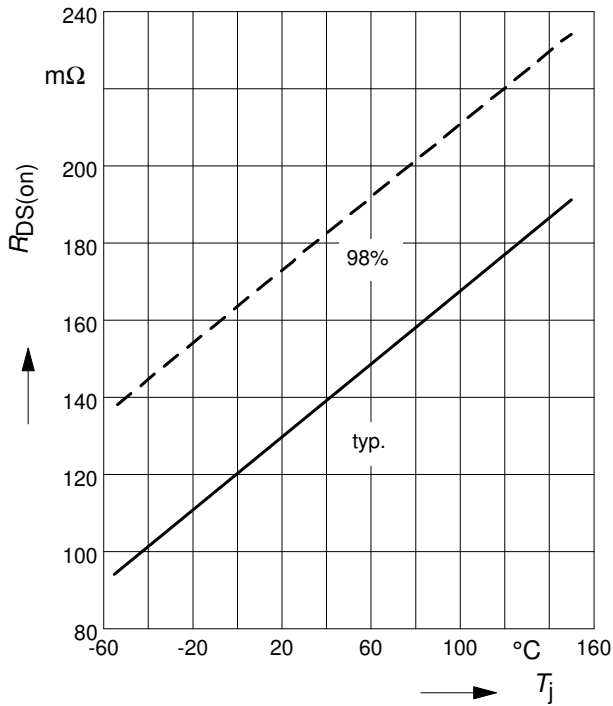
parameter:  $t_p = 80 \mu\text{s}$



### 9 Drain-source on-resistance

$$R_{DS(on)} = f(T_j)$$

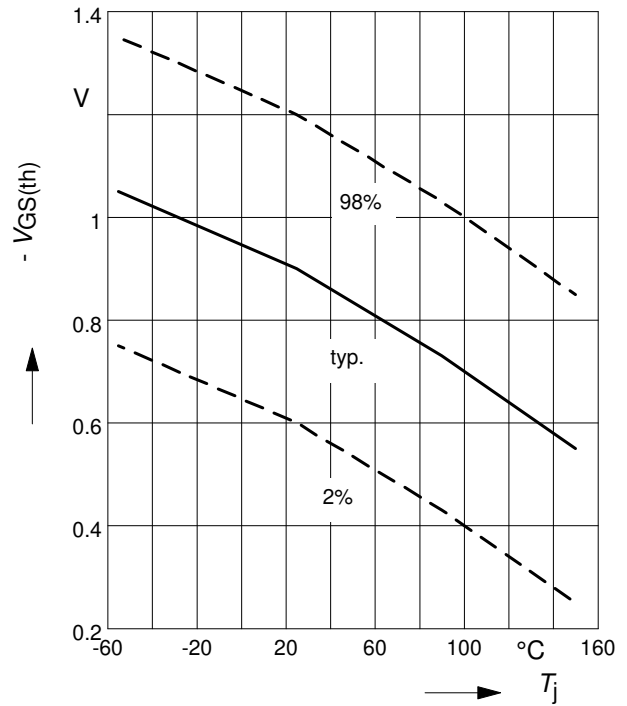
parameter:  $I_D = -1.5 \text{ A}$ ,  $V_{GS} = -4.5 \text{ V}$



### 10 Gate threshold voltage

$$V_{GS(th)} = f(T_j)$$

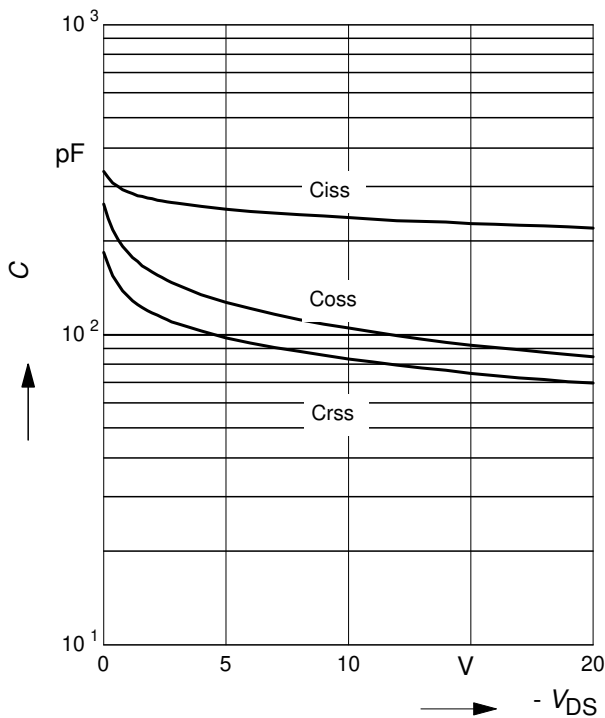
parameter:  $V_{GS} = V_{DS}$ ,  $I_D = -8 \mu\text{A}$



### 11 Typ. capacitances

$$C = f(V_{DS})$$

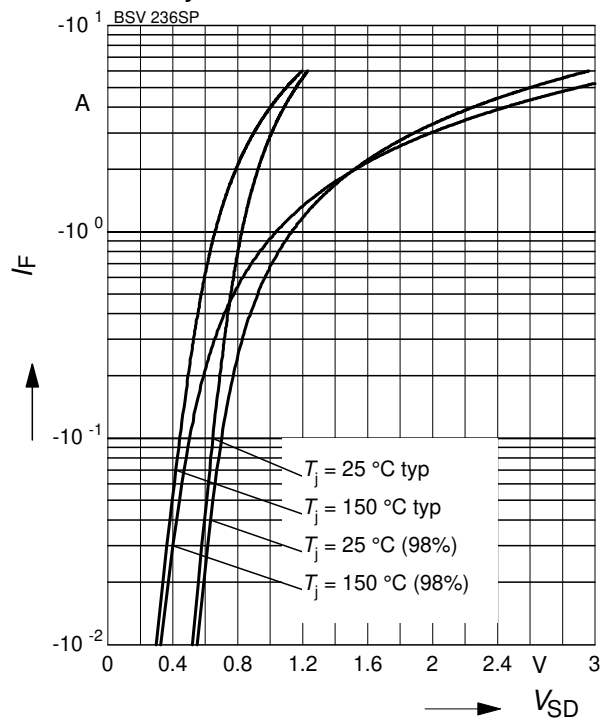
parameter:  $V_{GS}=0$ ,  $f=1 \text{ MHz}$



### 12 Forward character. of reverse diode

$$I_F = f(V_{SD})$$

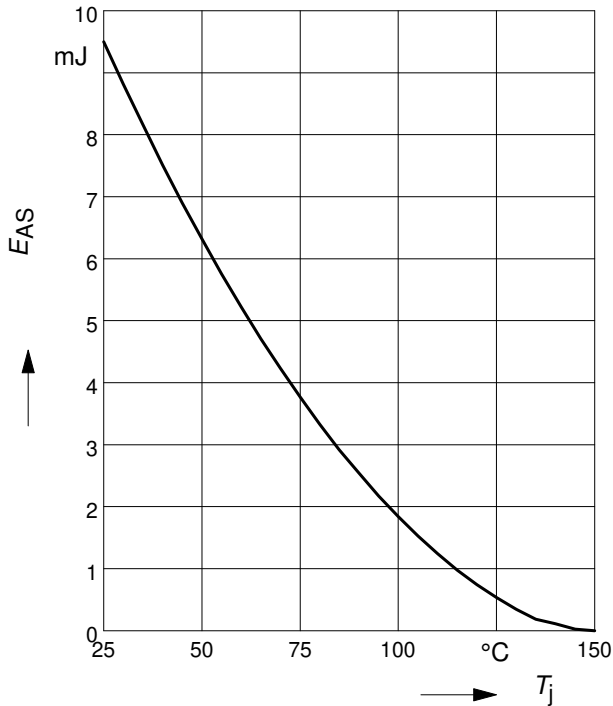
parameter:  $T_j$ ,  $t_p = 80 \mu\text{s}$



**13 Typ. avalanche energy**

$E_{AS} = f(T_j)$ , par.:  $I_D = -1.5\text{ A}$

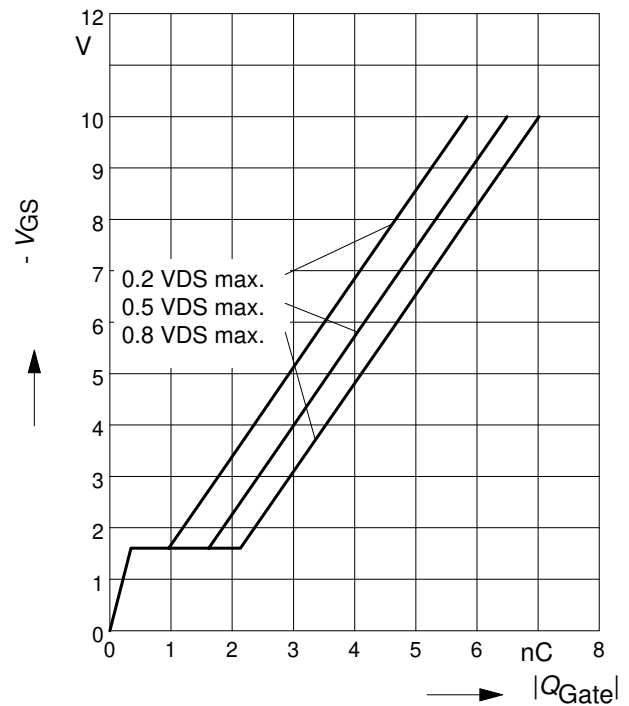
$V_{DD} = -10\text{ V}$ ,  $R_{GS} = 25\ \Omega$



**14 Typ. gate charge**

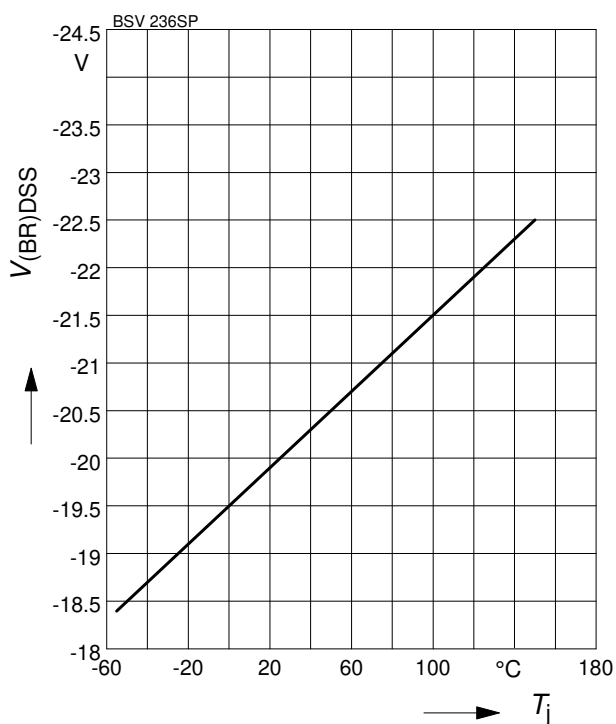
$|V_{GS}| = f(Q_{Gate})$

parameter:  $I_D = -1.5\text{ A}$  pulsed



**15 Drain-source breakdown voltage**

$V_{(BR)DSS} = f(T_j)$





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